ES1AF THRU ES1JF

Surface Mount Superfast Recovery Rectifier

Reverse Voltage – 50 to 600 V

Forward Current – 1 A

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode

Top View
Marking Code:
ES1AF~ES1JF: ES1A~ES1J
Simplified outline SMAF and symbol

FEATURES

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Superfast reverse recovery time
- Lead free in comply with EU RoHS 2011/65/EU directives

MECHANICAL DATA

- Case: SMAF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 27mg / 0.00095oz

Absolute Maximum Ratings and Characteristics

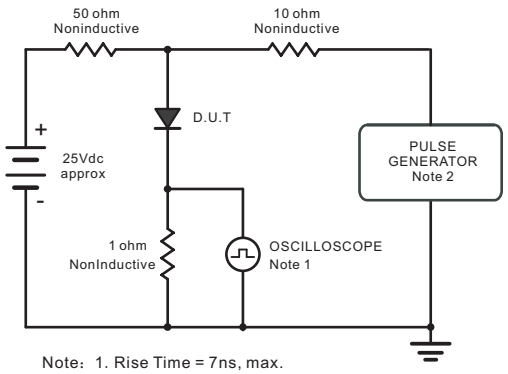
Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Parameter	Symbols	ES1AF	ES1BF	ES1CF	ES1DF	ES1EF	ES1GF	ES1JF	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	150	200	300	400	600	V
Maximum RMS voltage	V_{RMS}	35	70	105	140	210	280	420	V
Maximum DC Blocking Voltage	V_{DC}	50	100	150	200	300	400	600	V
Maximum Average Forward Rectified Current at T_c = 125 °C	$I_{F(AV)}$	1							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	30							A
Maximum Forward Voltage at 1 A	V_F	1				1.25		1.68	V
Maximum DC Reverse Current T_a = 25 °C at Rated DC Blocking Voltage T_a =125 °C	I_R	5 100							μA
Typical Junction Capacitance at V_R=4V, f=1MHz	C_j	15							pF
Maximum Reverse Recovery Time (1)	t_{rr}	35							ns
Typical Thermal Resistance (2)	$R_{\theta JA}$	80							°C/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150							°C

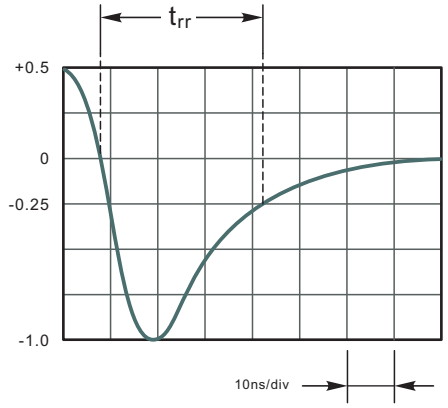
(1) Measured with I_F = 0.5 A, I_R = 1 A, I_{rr} = 0.25 A.

(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram



Note: 1. Rise Time = 7ns, max.
Input Impedance = 1megohm,22pF.
2. Ries Time =10ns, max.
Source Impedance = 50 ohms.



Set time Base for 10ns/div

Fig.2 Maximum Average Forward Current Rating

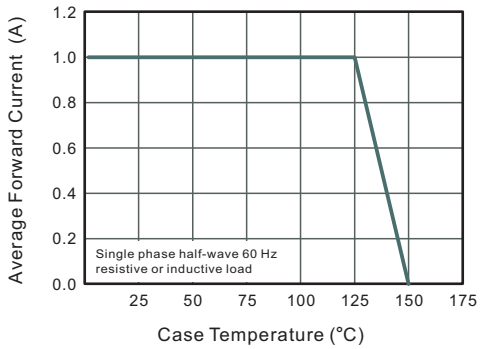


Fig.3 Typical Reverse Characteristics

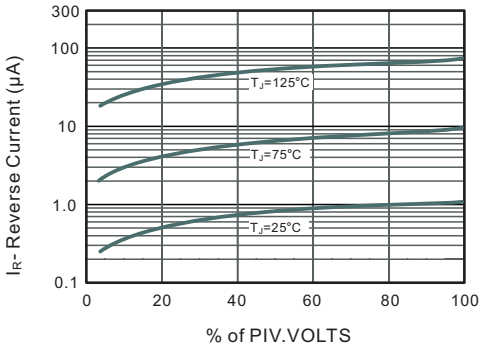


Fig.4 Typical Forward Characteristics

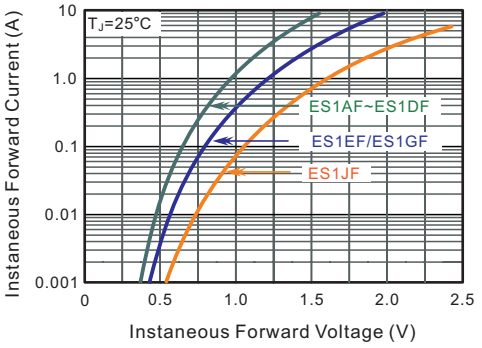


Fig.5 Typical Junction Capacitance

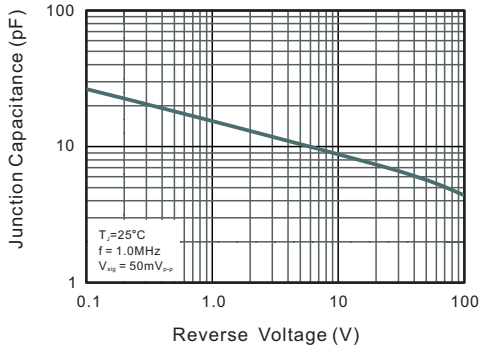
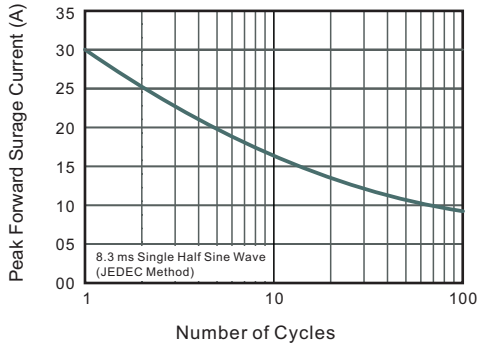


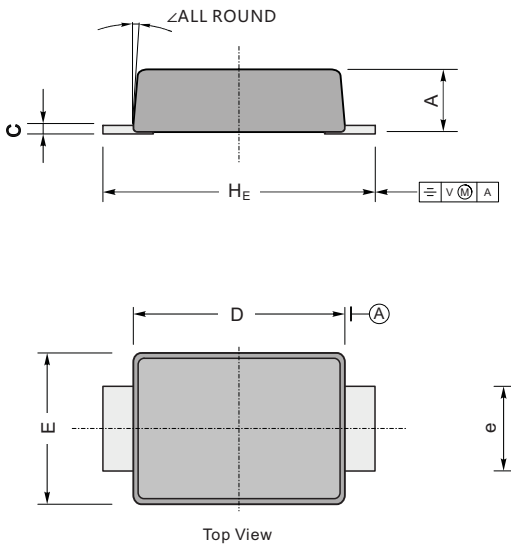
Fig.6 Maximum Non-Repetitive Peak Forward Surage Current



PACKAGE OUTLINE

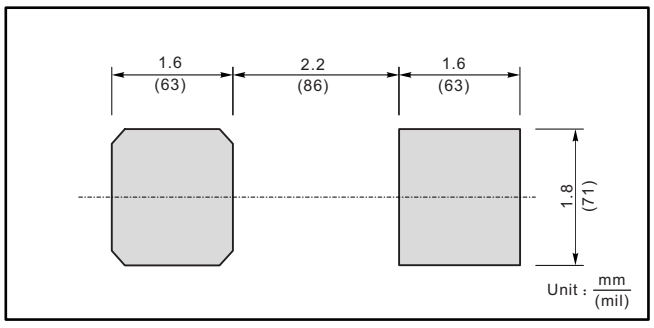
Plastic surface mounted package; 2 leads

SMAF



UNIT		A	C	D	E	e	g	H_E	∠
mm	max	1.2	0.20	3.7	2.7	1.6	1.2	4.9	7°
	min	0.9	0.12	3.3	2.4	1.3	0.8	4.4	
mil	max	47	7.9	146	106	63	47	193	
	min	35	4.7	130	94	51	31	173	

The recommended mounting pad size



Marking

Type number	Marking code
ES1AF	ES1A
ES1BF	ES1B
ES1CF	ES1C
ES1DF	ES1D
ES1EF	ES1E
ES1GF	ES1G
ES1JF	ES1J